



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	04/124/2013
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST202EBTR	DD6S*U495JC3	A	BO2A	04/124/2013
Amount	UoM	Unit type	ST ECOPACK Grade	
54.5	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.40,5.00,1.00	16	gull wing	
Comment	TSSOP 16 BODY 4.4 PITCH 0.65			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	DD65*U495JC3					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	2.869	mg	supplier	die	Silicon (Si)	7440-21-3		2.798	mg	975253	3681579
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.023	mg	8017	30263
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.009	mg	3137	11842
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.039	mg	13594	51316
Leadframe	Copper & its alloys	19.353	mg	supplier	alloy	Copper (Cu)	7440-50-8		18.5	mg	955924	24342105
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		0.577	mg	29814	759211
Leadframe				supplier	alloy	Magnesium (Mg)	7439-95-4		0.029	mg	1498	38158
Leadframe				supplier	alloy	Silicon (Si)	7440-21-3		0.125	mg	6459	164474
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.112	mg	5787	147368
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.004	mg	207	5263
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.003	mg	155	3947
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.003	mg	155	3947
Soft solder	Solder	0.926	mg	supplier	solder	Silver (Ag)	7440-22-4		0.843	mg	910367	1109211
Soft solder				supplier	solder	acrylate	Proprietary		0.046	mg	49676	60526
Soft solder				supplier	solder	Methacrylate	Proprietary		0.037	mg	39957	48684
Bonding wire	Other inorganic materials	0.109	mg	supplier	wire	Copper (Cu)	7440-50-8		0.109	mg	1000000	143421
encapsulation	Other Organic Materials	31.26	mg	supplier	mold compound	Silica, vitreous	60676-86-0		27.414	mg	876967	36071053
encapsulation				supplier	mold compound	Epoxy resin A	EC 413-900-7		1.251	mg	40019	1646053
encapsulation				supplier	mold compound	Epoxy resin B	29690-82-2		1.251	mg	40019	1646053
encapsulation				supplier	mold compound	phenol resin	Proprietary		0.938	mg	30006	1234211
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.094	mg	3007	123684
encapsulation				supplier	mold compound	additive	Proprietary		0.312	mg	9981	410526